Chip Monolithic Ceramic Capacitors

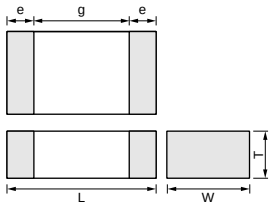
for Ultrasonic Sensors

■ Features

1. Proper compensation for ultrasonic sensors
2. Small chip size and high capacitance value

■ Application

Ultrasonic sensor
(back sonar, corner sonar, etc.)



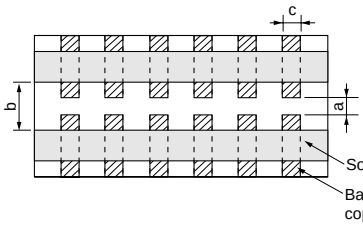
Part Number	Dimensions (mm)				
	L	W	T	e	g min.
GRM219	2.0 ±0.1	1.25 ±0.1	0.85 ±0.1	0.2 to 0.7	0.7

Part Number	TC Code	Rated Voltage (Vdc)	Capacitance (pF)	Length L (mm)	Width W (mm)	Thickness T (mm)
GRM2199E2A102KD42	ZLM (Murata)	100	1000 ±10%	2.0	1.25	0.85
GRM2199E2A152KD42	ZLM (Murata)	100	1500 ±10%	2.0	1.25	0.85

Specifications and Test Methods

No.	Item		Specifications	Test Method
1	Operating Temperature		−25℃ to +85℃	
2	Rated Voltage		See the previous pages.	The rated voltage is defined as the maximum voltage which may be applied continuously to the capacitor. When AC voltage is superimposed on DC voltage, V^{P-P} or V^{O-P}, whichever is larger, should be maintained within the rated voltage range.
3	Appearance		No defects or abnormalities	Visual inspection.
4	Dimensions		Within the specified dimensions	Using calipers.
5	Dielectric Strength		No defects or abnormalities	No failure should be observed when 300% of the rated voltage is applied between the terminations for 1 to 5 seconds, provided the charge/discharge current is less than 50mA.
6	Insulation Resistance (I.R.)		More than 10,000MΩ or 500Ω • F. (Whichever is smaller)	The insulation resistance should be measured with a DC voltage not exceeding the rated voltage at 20℃ and 75%RH max. and within 2 minutes of charging.
7	Capacitance		Within the specified tolerance	The capacitance/D.F. should be measured at 20℃ with 1±0.1kHz in frequency and 1±0.2Vr.m.s. in voltage.
8	Dissipation Factor (D.F.)		0.01 max.	
9	Capacitance Temperature Characteristics		Within −4,700 $^{+1,000}_{-2,500}$ ppm/℃ (at −25 to +20℃) Within −4,700 $^{+500}_{-1,000}$ ppm/℃ (at +20 to +85℃)	The temperature coefficient is determined using the capacitance measured in step 1 as a reference. When cycling the temperature sequentially from step 1 through 5, the capacitance should be within the specified tolerance for the temperature coefficient. The capacitance change should be measured after 5 min. at each specified temperature stage.
10	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the test jig (glass epoxy board) shown in Fig.1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.
11	Vibration Resistance	Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board) in the same manner and under the same conditions as (10). The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 minute. This motion should be applied for a period of 2 hours in each of 3 mutually perpendicular directions (total of 6 hours).
		Capacitance	Within the specified tolerance	
		D.F.	0.01 max.	

Step	Temperature(℃)
1	20±2
2	−25±3
3	20±2
4	85±3
5	20±2



Type	a	b	c
GRM21	1.2	4.0	1.65

(in mm)

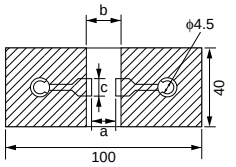
Fig.1

Continued on the following page.

Specifications and Test Methods

Continued from the preceding page.

No.	Item		Specifications	Test Method
12	Deflection		No cracking or marking defects should occur.	Solder the capacitor to the test jig (glass epoxy boards) shown in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.
13	Solderability of Termination		75% of the terminations are to be soldered evenly and continuously	Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Preheat at 80 to 120℃ for 10 to 30 seconds. After preheating, immerse in eutectic solder solution for 2±0.5 seconds at 230±5℃.
14	Resistance to Soldering Heat	Appearance	No defects or abnormalities	Preheat the capacitor at 120 to 150℃ for 1 minute. Immerse the capacitor in a eutectic solder solution at 270±5℃ for 10±0.5 seconds. Let sit at room temperature for 24±2 hours, then measure.
		Capacitance Change	Within ±7.5%	
		D.F.	0.01 max.	
		I.R.	More than 10,000MΩ or 500Ω • F (Whichever is smaller)	
		Dielectric Strength	No failure	
15	Temperature Cycle	Appearance	No defects or abnormalities	Fix the capacitor to the supporting jig in the same manner and under the same conditions as (11). Perform the five cycles according to the four heat treatments listed in the following table. Let sit for 24±2 hours at room temperature, then measure.
		Capacitance Change	Within ±7.5%	
		D.F.	0.01 max.	
		I.R.	More than 10,000MΩ or 500Ω • F (Whichever is smaller)	
		Dielectric Strength	No failure	
16	Humidity, Steady State	Appearance	No defects or abnormalities	Sit the capacitor at 40±2℃ and 90 to 95% humidity for 500±12 hours. Remove and let sit for 24±2 hours at room temperature, then measure.
		Capacitance Change	Within ±12.5%	
		D.F.	0.02 max.	
		I.R.	More than 1,000MΩ or 50Ω • F (Whichever is smaller)	
		Dielectric Strength	No failure	
17	Humidity Load	Appearance	No defects or abnormalities	Apply the rated voltage at 40±2℃ and 90 to 95% humidity for 500±12 hours. Remove and let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA.
		Capacitance Change	Within ±12.5%	
		D.F.	0.02 max.	
		I.R.	More than 500MΩ or 25Ω • F (Whichever is smaller)	
18	High Temperature Load	Appearance	No defects or abnormalities	Apply 200% of the rated voltage for 1,000±12 hours at 85±3℃. Let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA.
		Capacitance Change	Within ±12.5%	
		D.F.	0.02 max.	
		I.R.	More than 1,000MΩ or 50Ω • F (Whichever is smaller)	



Type	a	b	c
GRM21	1.2	4.0	1.65

(in mm)

Fig. 2

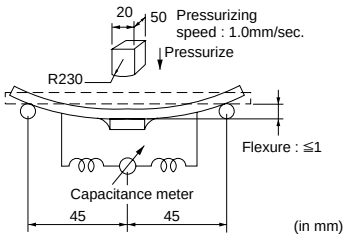


Fig.3

Step	1	2	3	4
Temp. (℃)	-25^{+0}_{-3}	RoomTemp.	85^{+3}_{-0}	RoomTemp.
Time (min.)	30±3	2 to 3	30±3	2 to 3